



US0D1051864S

(12)

United States Design Patent

Lai et al.

(10)

Patent No.:

US D1,051,864 S

(45)

Date of Patent:

** Nov. 19, 2024

(54) HEAT DISSIPATION MODULE

(71) Applicant: Acer Incorporated, New Taipei (TW)

(72) Inventors: Wei-Yu Lai, New Taipei (TW);
Yi-Heng Lee, New Taipei (TW)

(73) Assignee: Acer Incorporated, New Taipei (TW)

(**) Term: 15 Years

(21) Appl. No.: 29/834,940

(22) Filed: Apr. 14, 2022

(30) Foreign Application Priority Data

Feb. 8, 2022 (TW) 111300616

(51) LOC (14) Cl. 13-03

(52) U.S. Cl.
USPC D13/179

(58) Field of Classification Search
USPC D13/179, 182; D23/358, 370, 379, 411,
D23/412; D14/435
CPC H01L 23/367; H01L 23/3672; H01L
23/4093; H01L 23/467; F28F 2215/00;
F28F 2215/08; H05K 7/20; H05K
7/20009; H05K 7/20127; H05K 7/20136;
H05K 7/20145; H05K 7/20154; H05K
7/20163; H05K 7/20172; H05K 7/20181;
H05K 7/2019; H05K 7/202; H05K
7/20209
See application file for complete search history.

(56) References Cited

U.S. PATENT DOCUMENTS

D396,276 S * 7/1998 Horng D23/370
D398,392 S * 9/1998 Horng D23/370
D398,977 S * 9/1998 Horng D23/370
D398,978 S * 9/1998 Horng D23/370
D399,946 S * 10/1998 Horng D23/370
D400,665 S * 11/1998 Horng D23/370

D401,686 S * 11/1998 Horng D23/370
5,873,406 A * 2/1999 Horng H01L 23/467
257/E23.099
D408,514 S * 4/1999 Horng D23/370
5,940,269 A * 8/1999 Ko H01L 23/467
174/16.3
D418,216 S * 12/1999 Horng D23/370
6,135,200 A * 10/2000 Okochi H01L 23/467
257/E23.099
6,137,680 A * 10/2000 Kodaira H01L 23/4093
174/16.3
6,252,770 B1 * 6/2001 Yu G06F 1/20
361/679.48
D570,794 S * 6/2008 Horng D13/179
(Continued)

OTHER PUBLICATIONS

[Up Your Game], date first available Nov. 26, 2020 [online],
[retrieved Nov. 13, 2023]. Retrieved from internet, <<https://global.aorus.com/blog-detail.php?i=865>> (Year: 2020).*

Primary Examiner — Leanne Was-Englehart

(74) Attorney, Agent, or Firm — JCIPRNET

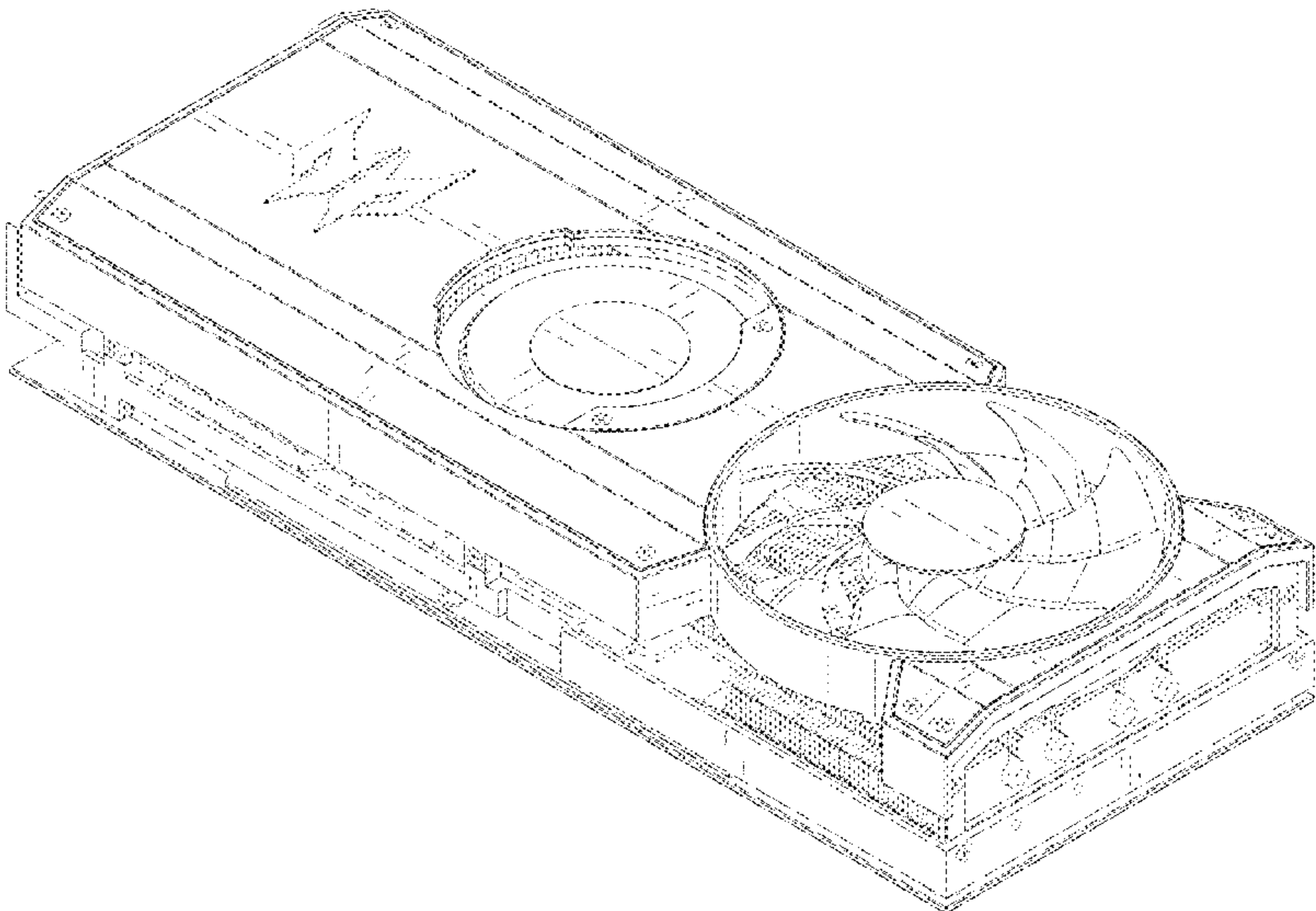
(57) CLAIM

The ornamental design for a heat dissipation module as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a heat dissipation module showing our new design;
FIG. 2 is another perspective view thereof;
FIG. 3 is a front view thereof;
FIG. 4 is a rear view thereof;
FIG. 5 is a left side view thereof;
FIG. 6 is a right side view thereof;
FIG. 7 is a top view thereof; and,
FIG. 8 is a bottom view thereof.
The dashed broken lines illustrate portions of the heat dissipation module that form no part of the claimed design.

1 Claim, 6 Drawing Sheets



(56) **References Cited**

U.S. PATENT DOCUMENTS

D570,795	S *	6/2008	Horng		D13/179
D571,313	S *	6/2008	Horng		D13/179
D571,314	S *	6/2008	Horng		D13/179
7,782,617	B2 *	8/2010	Li		G06F 1/20
					165/104.33
9,036,348	B2 *	5/2015	Huang		G06F 1/20
					417/423.15
D928,161	S *	8/2021	Fan		D13/179
D979,571	S *	2/2023	Feng		D14/435
D997,109	S *	8/2023	Tso		D23/370
2018/0196483	A1 *	7/2018	Han		H01L 23/3672
2018/0203493	A1 *	7/2018	Han		H05K 7/20209
2018/0213680	A1 *	7/2018	Han		H05K 7/20509
2021/0116979	A1 *	4/2021	Walker		H05K 7/20145
2023/0171914	A1 *	6/2023	Lin		H05K 7/2039
					361/679.47
2023/0205285	A1 *	6/2023	Walker		H02J 7/0045
					361/679.48

* cited by examiner

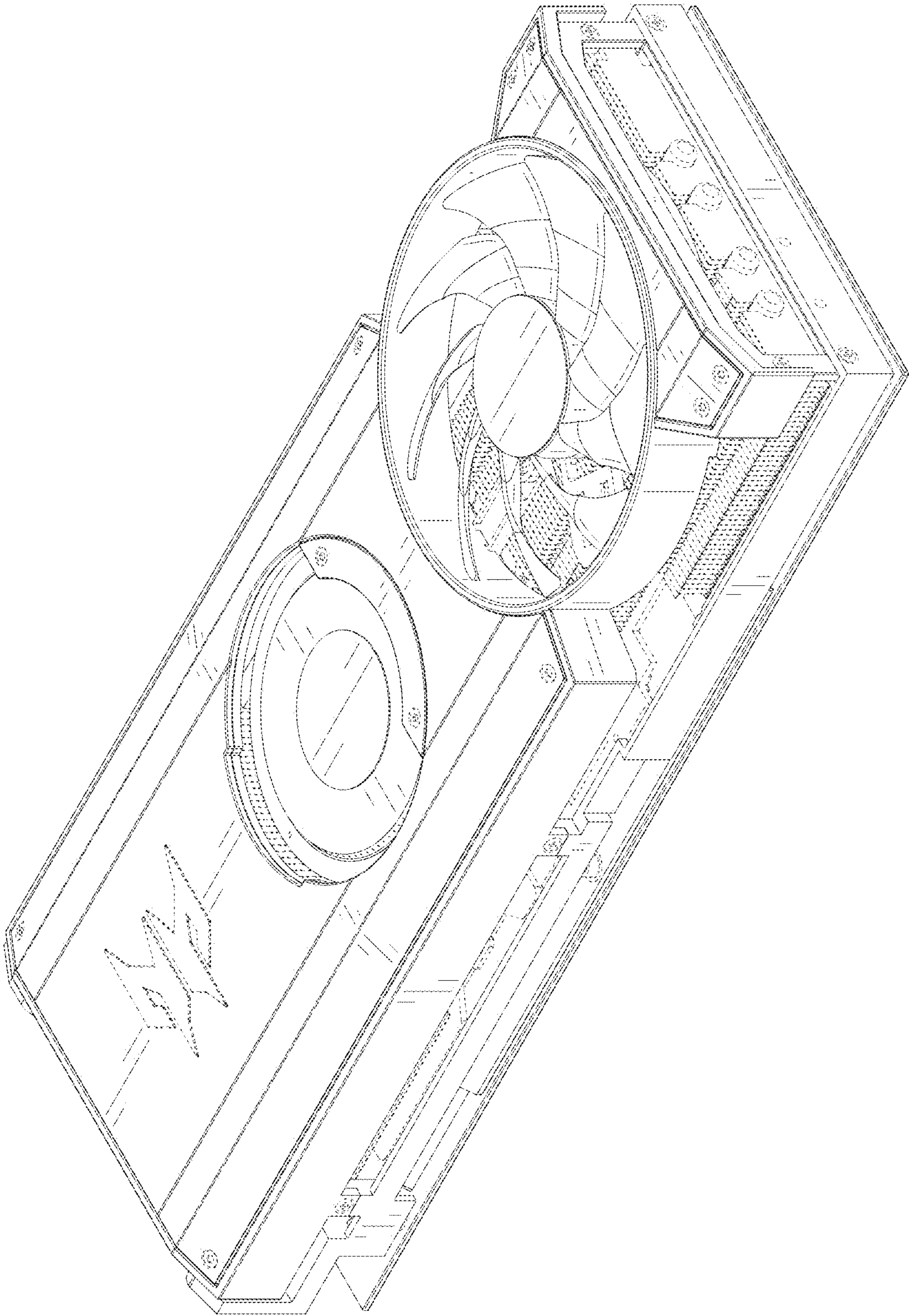


FIG. 1

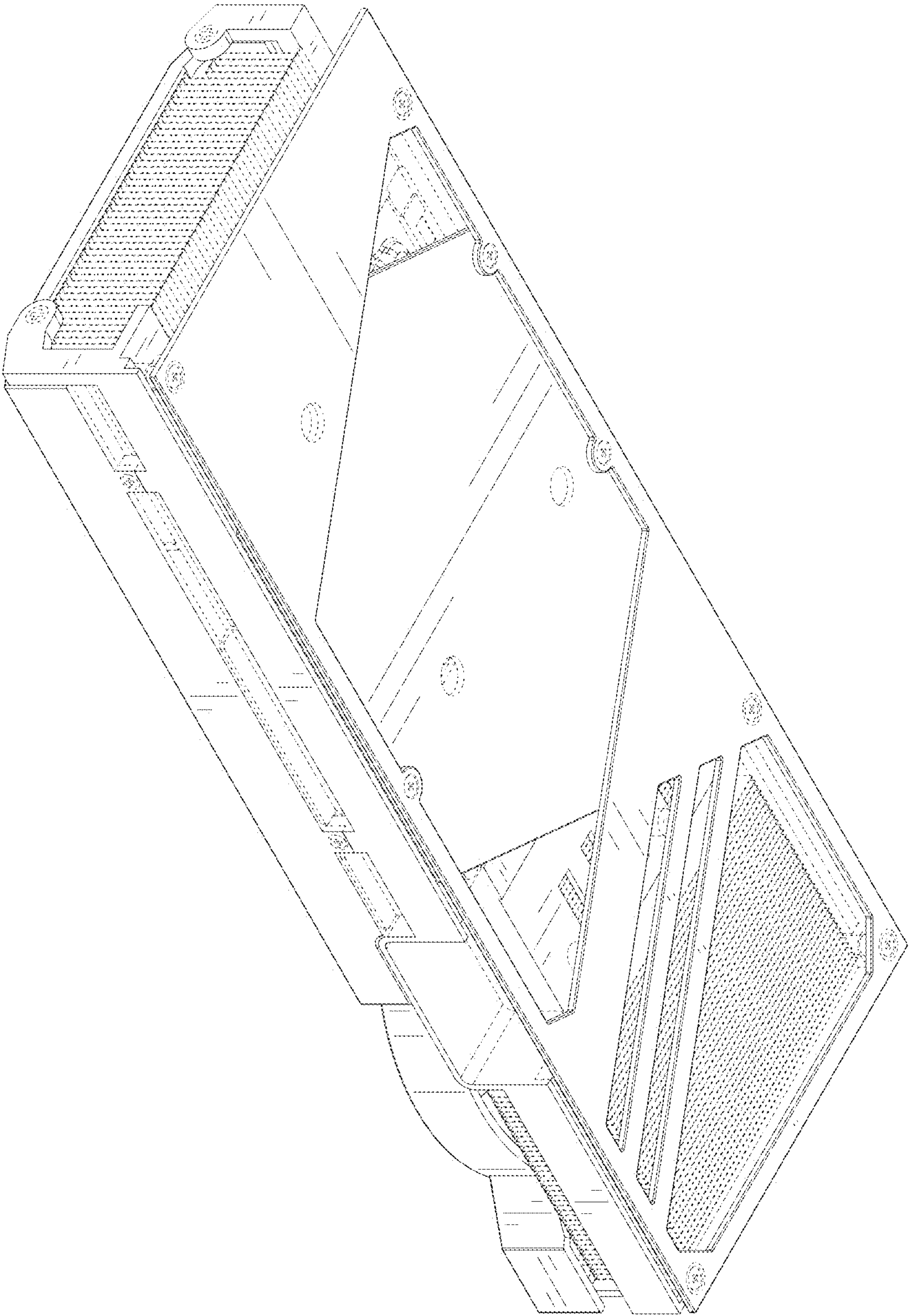


FIG. 2

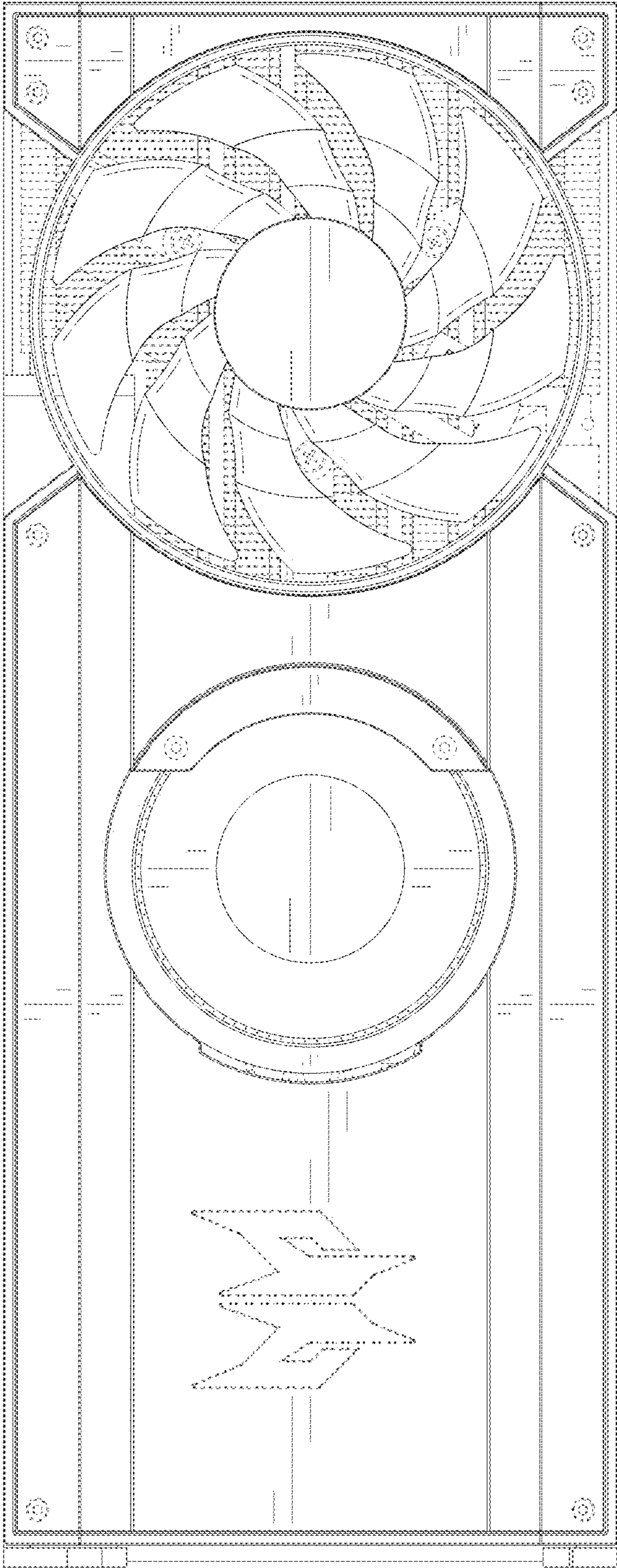


FIG. 3

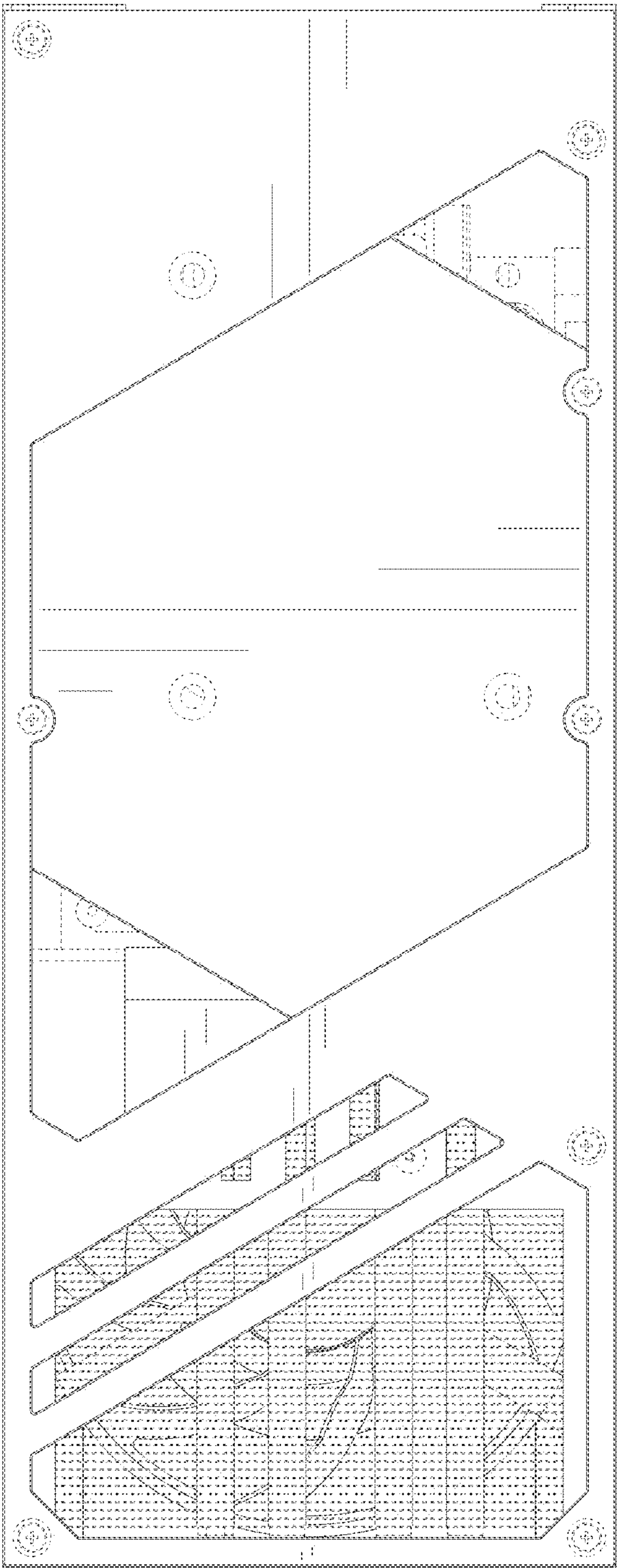


FIG. 4

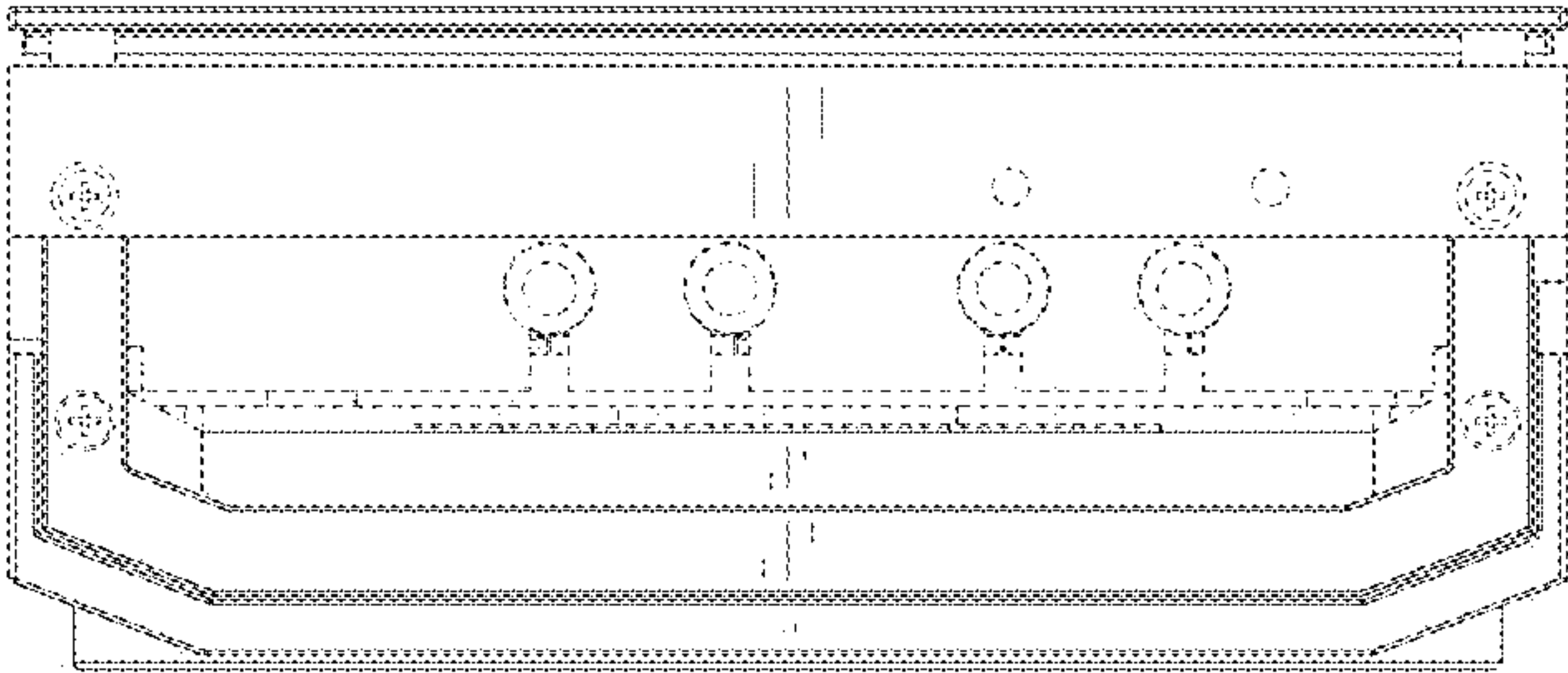


FIG. 6

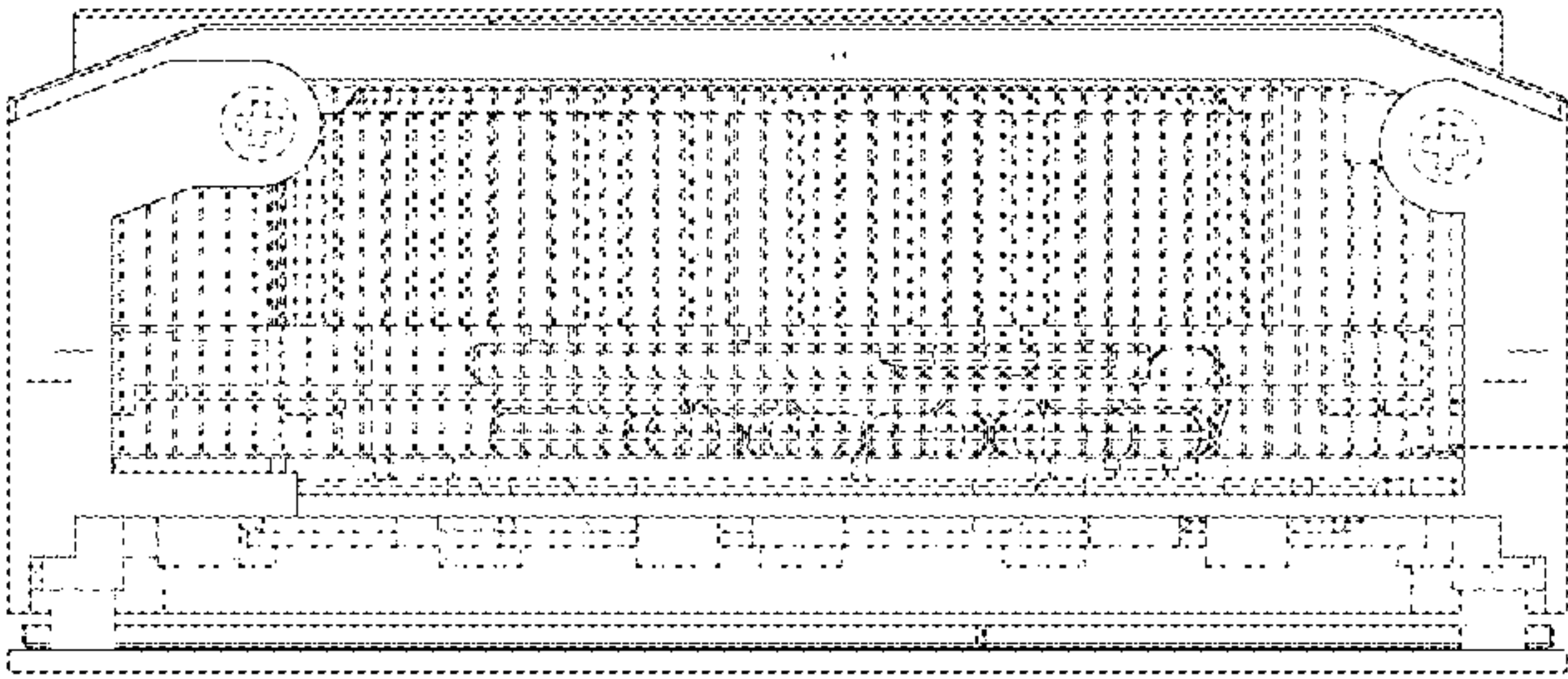


FIG. 5

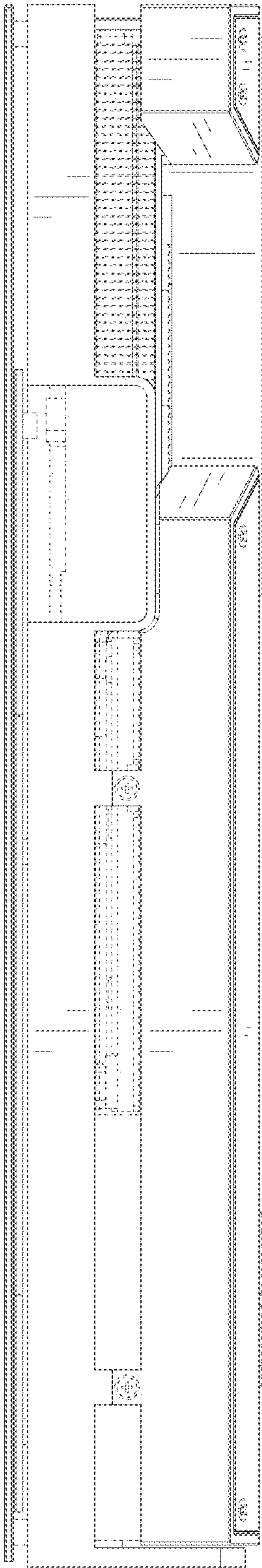


FIG. 7

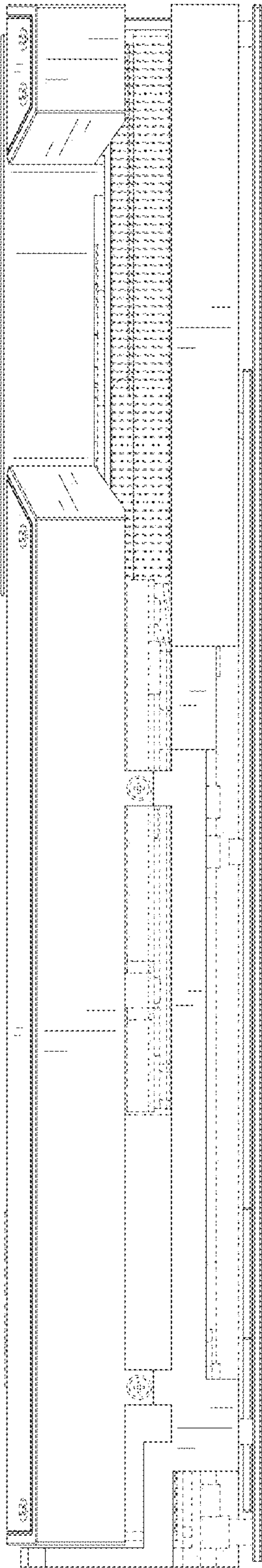


FIG. 8